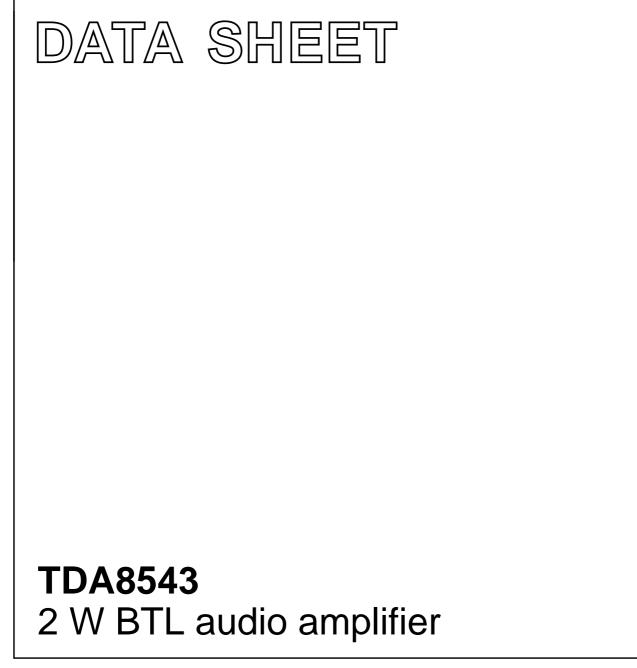
INTEGRATED CIRCUITS



Product specification File under Integrated Circuits, IC01 1997 Jun 12



TDA8543

FEATURES

- Flexibility in use
- Few external components
- Low saturation voltage of output stage
- · Gain can be fixed with external resistors
- Standby mode controlled by CMOS compatible levels
- · Low standby current
- No switch-on/switch-off plops
- High supply voltage ripple rejection
- Protected against electrostatic discharge
- Outputs short-circuit safe to ground, V_{CC} and across the load
- Thermally protected.

QUICK REFERENCE DATA

GENERAL DESCRIPTION

The TDA8543(T) is a one channel audio power amplifier for an output power of 2 W with an 8 Ω load at a 7.5 V supply. The circuit contains a BTL amplifier with a complementary PNP-NPN output stage and standby/mute logic. The TDA8543T comes in a 16 pin SO package and the TDA8543 in a 16 pin DIP package.

APPLICATIONS

- Portable consumer products
- Personal computers
- Telephony.

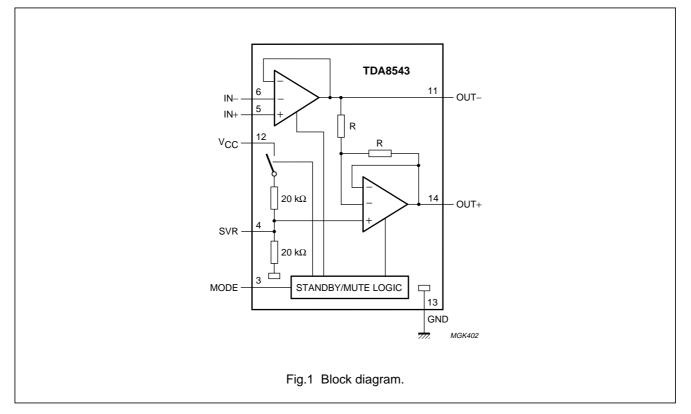
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CC}	supply voltage		2.2	5	18	V
lq	quiescent current	V _{CC} = 5 V	_	8	12	mA
I _{stb}	standby current		-	-	10	μA
Po	output power	THD = 10%				
		$R_{L} = 8 \Omega; V_{CC} = 5 V$	1	1.2	-	W
		$R_{L} = 8 \Omega; V_{CC} = 7.5 V$	-	2.2	-	W
		$R_L = 16 \Omega; V_{CC} = 9 V$	-	2.0	-	W
THD	total harmonic distortion	$P_0 = 0.5 W$	_	0.15	_	%
SVRR	supply voltage ripple rejection		50	-	_	dB

ORDERING INFORMATION

ТҮРЕ		PACKAGE	
NUMBER	NAME	DESCRIPTION	VERSION
TDA8543T	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
TDA8543	DIP16	plastic dual in-line package; 16 leads (300 mil); long body	SOT38-1

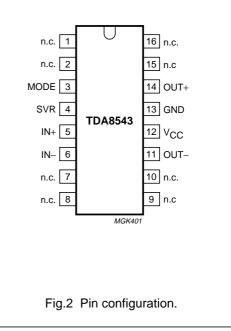
TDA8543

BLOCK DIAGRAM



PINNING

SYMBOL	PIN	DESCRIPTION
n.c.	1	not connected
n.c.	2	not connected
MODE	3	operating mode select (standby, mute, operating)
SVR	4	half supply voltage, decoupling ripple rejection
IN+	5	positive input
IN–	6	negative input
n.c.	7	not connected
n.c.	8	not connected
n.c.	9	not connected
n.c.	10	not connected
OUT-	11	negative loudspeaker terminal
V _{CC}	12	supply voltage
GND	13	ground
OUT+	14	positive loudspeaker terminal
n.c.	15	not connected
n.c.	16	not connected



TDA8543

FUNCTIONAL DESCRIPTION

The TDA8543(T) is a BTL audio power amplifier capable of delivering an output power between 1 and 2 W, depending on supply voltage, load resistance and package. Using the MODE pin the device can be switched to standby and mute condition. The device is protected by an internal thermal shutdown protection mechanism.

The gain can be set within a range from 6 dB to 30 dB by external feedback resistors.

Power amplifier

The power amplifier is a Bridge Tied Load (BTL) amplifier with a complementary PNP-NPN output stage.

The voltage loss on the positive supply line is the saturation voltage of a PNP power transistor, on the negative side the saturation voltage of an NPN power transistor.

Mode select pin

The device is in standby mode (with a very low current consumption) if the voltage at the MODE pin is >(V_{CC} - 0.5 V), or if this pin is floating. At a MODE voltage level of less than 0.5 V the amplifier is fully operational.

In the range between 1.5 V and V_{CC} – 1.5 V the amplifier is in mute condition. The mute condition is useful to suppress plop noise at the output, caused by charging of the input capacitor.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	supply voltage	operating	-0.3	+18	V
VI	input voltage		-0.3	V _{CC} + 0.3	V
I _{ORM}	repetitive peak output current		-	1	A
T _{stg}	storage temperature	non-operating	-55	+150	°C
T _{amb}	operating ambient temperature		-40	+85	°C
V _{psc}	AC and DC short-circuit safe voltage		-	10	V
P _{tot}	total power dissipation	SO16	-	1.2	W
		DIP16	-	2.2	W

QUALITY SPECIFICATION

In accordance with *"SNW-FQ-611-E"*. The number of the quality specification can be found in the *"Quality Reference Handbook"*. The handbook can be ordered using the code 9397 750 00192.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	in free air		
	TDA8543T (SO16)		100	K/W
	TDA8543 (DIP16)		55	K/W

2 W BTL audio amplifier

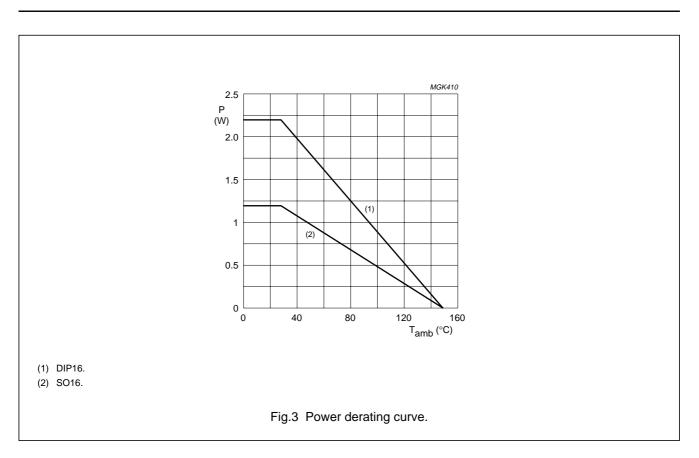


Table 1

			CONTINUOUS SINE WAVE DRIVEN			
V _{cc} (V)	R _L (Ω)	P _o (W) ⁽¹⁾	D (141)	T _{amb(max)} (°C)		
			P _{max} (W)	SO16	DIP16	
5	8	1.2	0.7	80	112	
7.5	8	2.2	1.6	_	62	
7.5	16	1.4	0.9	60	100	
9	16	2.0	1.3	_	78	
9	25	1.3	0.9	60	100	

Note

1. At THD = 10%; BTL.

TDA8543

DC CHARACTERISTICS

 V_{CC} = 5 V; T_{amb} = 25 °C; R_L = 8 Ω ; V_{MODE} = 0 V; G = 20 dB; measured in test circuit Fig.4; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CC}	supply voltage	operating	2.2	5	18	V
lq	quiescent current	R _L = ∞; note 1	-	8	12	mA
I _{stb}	standby current	$V_{MODE} = V_{CC}$	-	-	10	μA
Vo	DC output voltage	note 2	-	2.2	-	V
V _{OUT+} – V _{OUT-}	differential output voltage offset		-	-	50	mV
I _{IN+} , I _{IN-}	input bias current		_	-	500	nA
V _{MODE}	input voltage mode select	operating	0	-	0.5	V
		mute	1.5	_	V _{CC} – 1.5	V
		standby	V _{CC} - 0.5	-	V _{CC}	V
I _{MODE}	input current mode select	$0 < V_{MODE} < V_{CC}$	-	_	20	μA

Notes

- 1. With a load connected at the outputs the quiescent current will increase, the maximum of this increase being equal to the DC output offset voltage divided by R_L .
- 2. The DC output voltage with respect to ground is approximately $0.5 \times V_{CC}$.

AC CHARACTERISTICS

 V_{CC} = 5 V; T_{amb} = 25 °C; R_L = 8 Ω ; f = 1 kHz; V_{MODE} = 0 V; G = 20 dB; measured in test circuit Fig.4; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Po	output power	THD = 10%;				
		$V_{CC} = 5 \text{ V}; \text{ R}_{L} = 8 \Omega$	1	1.2	-	W
		$V_{CC} = 7.5 \text{ V}; \text{ R}_{L} = 8 \Omega$	_	2.2	-	W
		V_{CC} = 9 V; R_{L} = 16 Ω	-	2.0	-	W
		THD = 0.5%;				
		$V_{CC} = 5 \text{ V}; \text{ R}_{L} = 8 \Omega$	0.6	0.9	-	W
		V_{CC} = 7.5 V; R_L = 8 Ω	-	1.7	-	W
		V_{CC} = 9 V; R_{L} = 16 Ω	-	1.4	-	W
THD	total harmonic distortion	$P_0 = 0.5 W$	-	0.15	0.3	%
G _v	closed loop voltage gain	note 1	6	-	30	dB
Zi	differential input impedance		-	100	-	kΩ
V _{no}	noise output voltage	note 2	-	-	100	μV
SVRR	supply voltage ripple rejection	note 3	50	-	-	dB
		note 4	40	_	-	dB
Vo	output voltage in mute condition	note 5	-	_	200	μV

2 W BTL audio amplifier

Notes to the AC characteristics

- 1. Gain of the amplifier is $2 \times \frac{R2}{R1}$ in test circuit of Fig.4.
- 2. The noise output voltage is measured at the output in a frequency range from 20 Hz to 20 kHz (unweighted), with a source impedance of $R_S = 0 \Omega$ at the input.
- 3. Supply voltage ripple rejection is measured at the output, with a source impedance of $R_S = 0 \Omega$ at the input. The ripple voltage is a sine wave with a frequency of 1 kHz and an amplitude of 100 mV (RMS), which is applied to the positive supply rail.
- 4. Supply voltage ripple rejection is measured at the output, with a source impedance of $R_S = 0 \Omega$ at the input. The ripple voltage is a sine wave with a frequency between 100 Hz and 20 kHz and an amplitude of 100 mV (RMS), which is applied to the positive supply rail.
- 5. Output voltage in mute position is measured with an input voltage of 1 V (RMS) in a bandwidth of 20 kHz, so including noise.

TEST AND APPLICATION INFORMATION

Test conditions

Because the application can be either Bridge Tied Load (BTL) or Single-Ended (SE), the curves of each application are shown separately.

The thermal resistance = 55 K/W for the DIP16 envelope; the maximum sine wave power dissipation

for $T_{amb} = 25 \text{ °C}$ is: $\frac{150 - 25}{55} = 2.27 \text{ W}$

For $T_{amb} = 60 \text{ °C}$ the maximum total power dissipation is: $\frac{150-60}{55} = 1.63 \text{ W}$

55 [–] 1.00 W

See the power derating curve illustrated in Fig.3.

BTL application

 T_{amb} = 25 °C if not specially mentioned, V_{CC} = 5 V, f = 1 kHz, R_L = 8 Ω , G_v = 20 dB, audio band-pass 22 Hz to 22 kHz.

The BTL application diagram is shown in Fig.4.

The quiescent current has been measured without any load impedance. The total harmonic distortion as a function of frequency was measured with a low-pass filter of 80 kHz. The value of capacitor C2 influences the behaviour of the SVRR at low frequencies, increasing the value of C2 increases the performance of the SVRR. The figure of the mode select voltage (V_{ms}) as a function of the supply voltage shows three areas; operating, mute and standby. It shows, that the DC-switching levels of the mute and standby respectively depends on the supply voltage level.

SE application

 $\label{eq:Tamb} \begin{array}{l} \mathsf{T}_{amb} = 25 \ ^\circ \text{C} \ \text{if not specially mentioned, } \mathsf{V}_{CC} = 7.5 \ \text{V}, \\ \mathsf{f} = 1 \ \text{kHz}, \ \mathsf{R}_L = 4 \ \Omega, \ \mathsf{G}_v = 20 \ \text{dB}, \ \text{audio band-pass} \\ 22 \ \text{Hz} \ \text{to} \ 22 \ \text{kHz}. \end{array}$

The SE application diagram is shown in Fig.14.

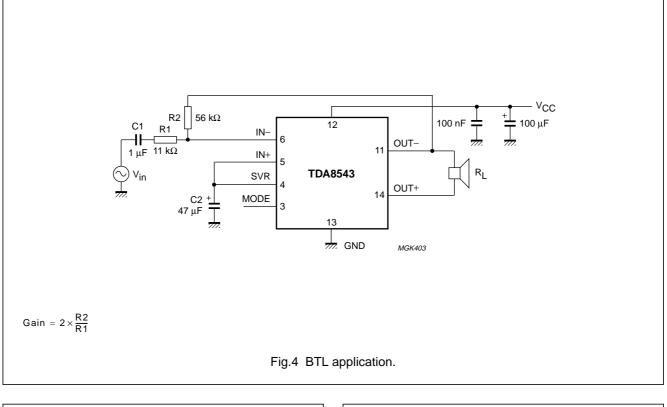
The capacitor value of C3 in combination with the load impedance determines the low frequency behaviour. The total harmonic distortion as a function of frequency was measured with low-pass filter of 80 kHz. The value of capacitor C2 influences the behaviour of the SVRR at low frequencies, increasing the value of C2 increases the performance of the SVRR.

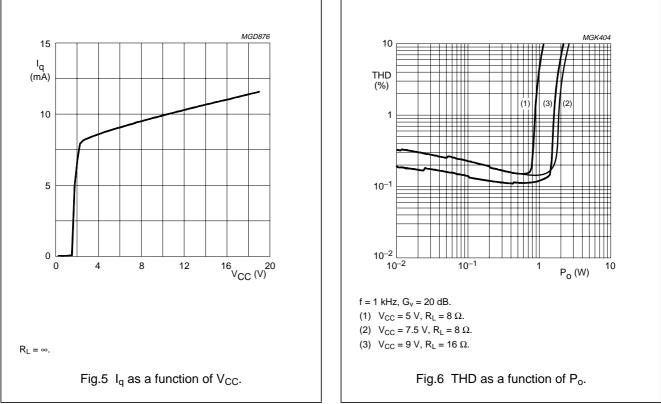
General remark

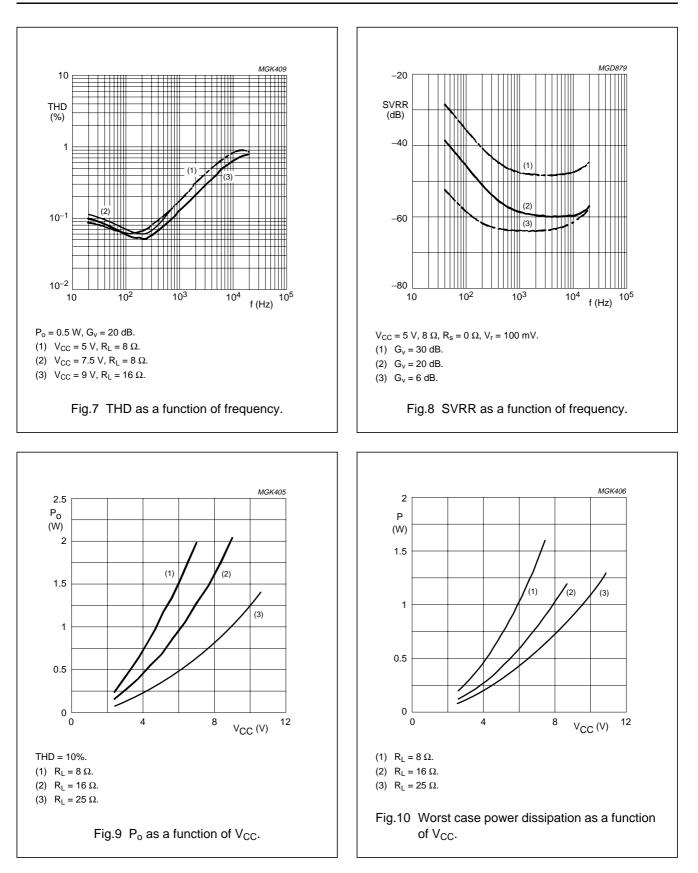
The frequency characteristic can be adapted by connecting a small capacitor across the feedback resistor. To improve the immunity of HF radiation in radio circuit applications, a small capacitor can be connected in parallel with the feedback resistor; this creates a low-pass filter.

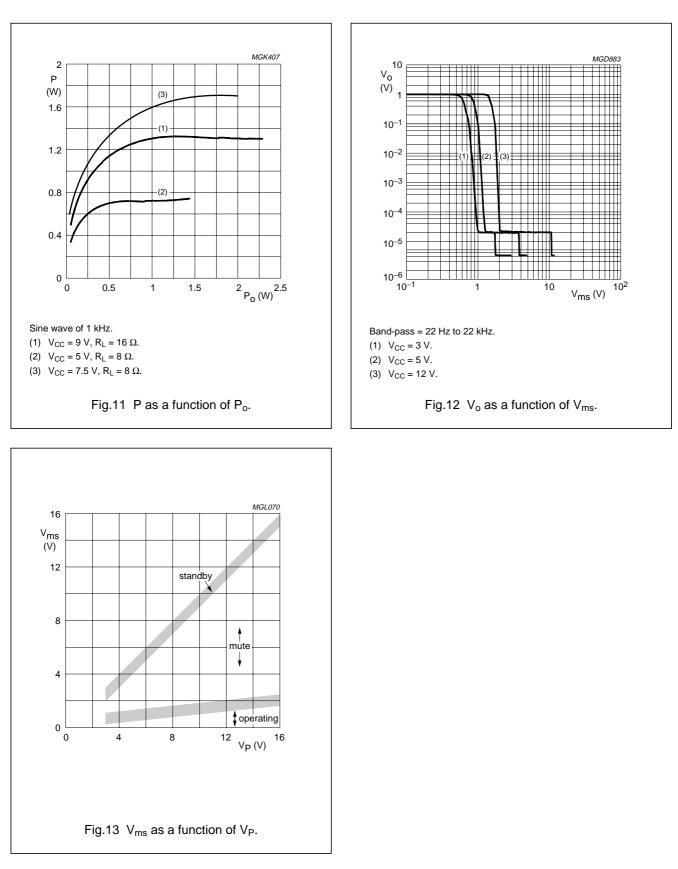
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BTL APPLICATION



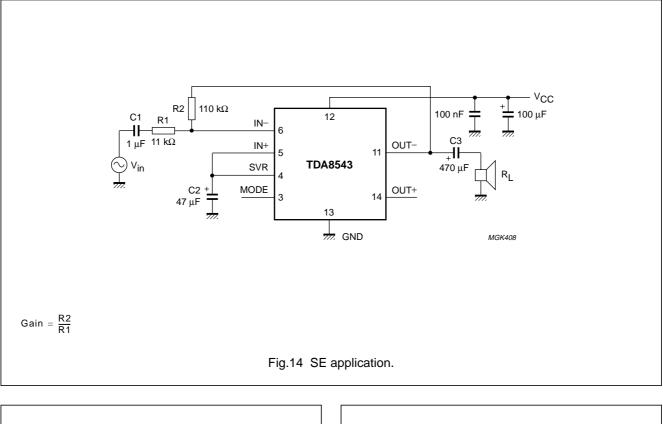


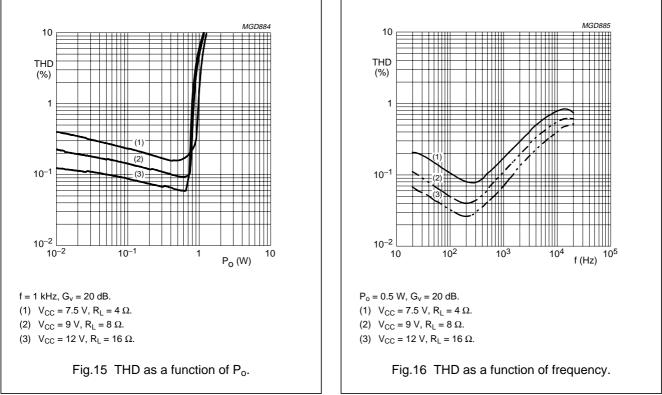


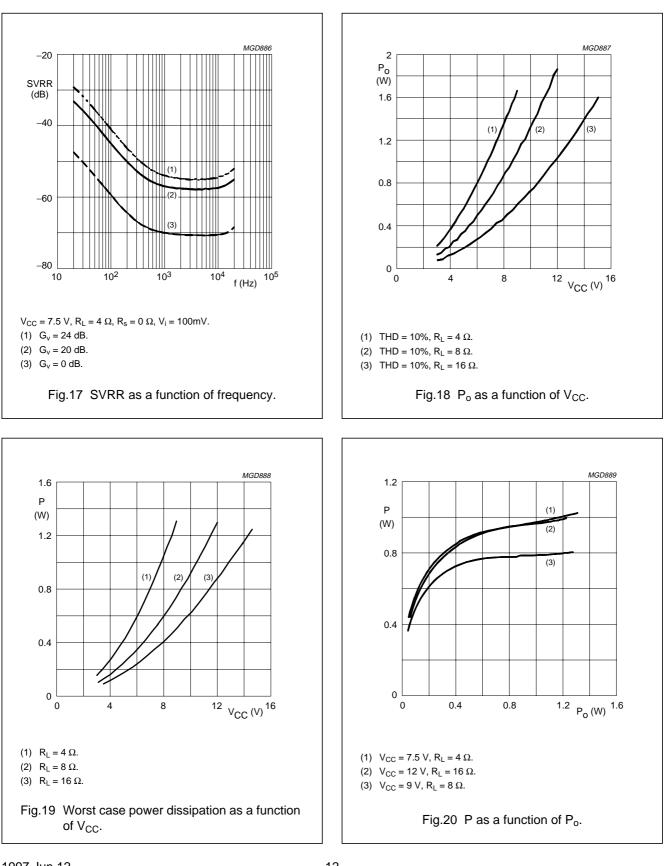


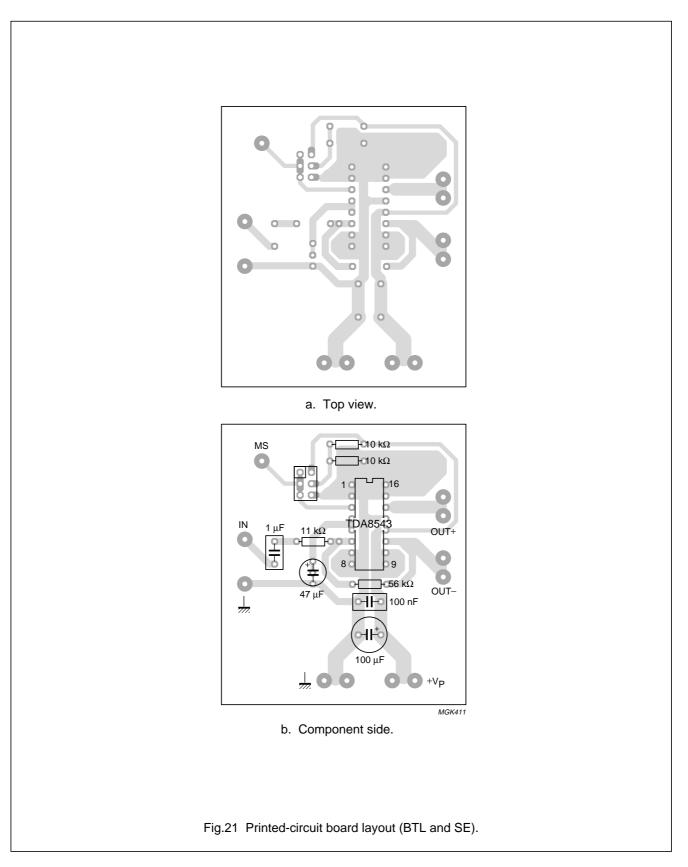
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SE APPLICATION





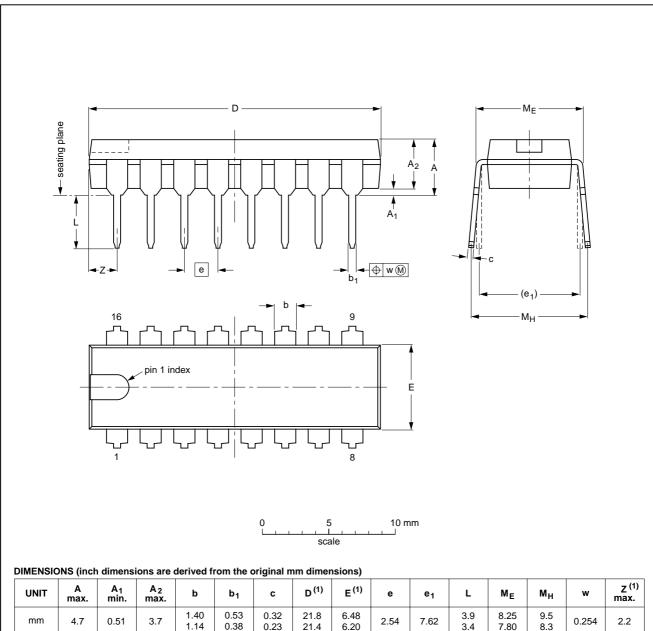




2 W BTL audio amplifier

PACKAGE OUTLINES

DIP16: plastic dual in-line package; 16 leads (300 mil); long body



N	ote

inches

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

0.15

0.020

0.19

0.055

0.045

0.021

0.015

0.013

0.009

0.86

0.84

0.26

0.24

0.10

0.30

0.15

0.13

0.32

0.31

0.37

0.33

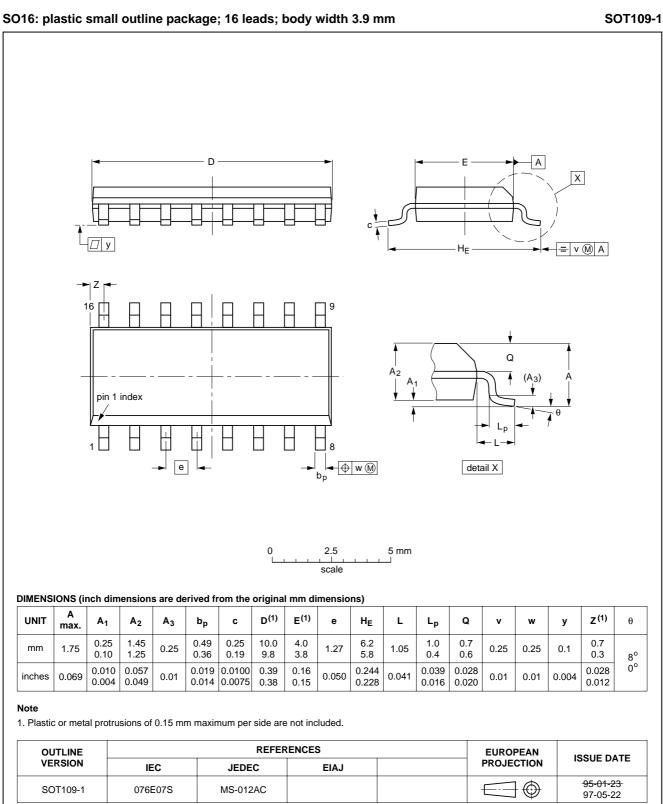
0.087

0.01

OUTLINE		REFERENCES			EUROPEAN ISSUE DAT	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE
SOT38-1	050G09	MO-001AE				-92-10-02 95-01-19

SOT38-1

2 W BTL audio amplifier



TDA8543

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

DIP

SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\,max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than $300 \,^{\circ}$ C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 $^{\circ}$ C, contact may be up to 5 seconds.

SO

REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied

to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 $^{\circ}$ C.

WAVE SOLDERING

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

TDA8543

DEFINITIONS

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification This data sheet contains preliminary data; supplementary data may be published later.				
Product specification This data sheet contains final product specifications.				
Limiting values				
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.				
Application information				

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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